

### 2.5X2.0mm SURFACE MOUNT LED LAMP

## PRELIMINARY SPEC



**ATTENTION OBSERVE PRECAUTIONS** FOR HANDLING ELECTROSTATIC DISCHARGE **SENSITIVE DEVICES** 

Part Number: AT2520QW10ZS-350MA

White

### **Features**

- Dimension: 2.5mmx 2.0mm x 0.8mm.
- Low thermal resistance.
- Ceramic package with silicone resin.
- Higher brightness LED flash.
- Small package with high efficiency.
- Surface mount technology.
- ESD protection.
- Radiation patterns optimal for camera flash.
- Enables higher resolution pictures in darken environments.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 2a.
- Soldering methods: IR reflow soldering.
- RoHS compliant.

## **Application Note**

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically

## **Typical Applications**

Digital still cameras

Camera-phones

**PDAs** 

Room lighting

Architectural lighting

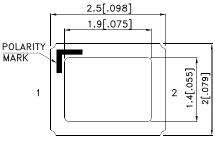
Decorative/pathway lighting

Front panel backlight

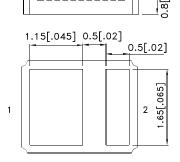
Exterior automotive lighting:

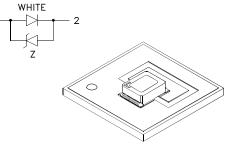
(brake lights, turn lights, backlighting)

## **Package Dimensions**









- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.25 (0.01")$  unless otherwise noted.
- 3. Specifications are subject to change without notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.





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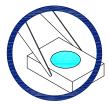
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## **Handling Precautions**

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

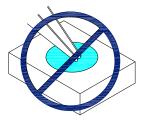
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

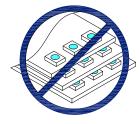


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

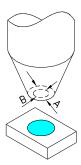




Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



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## **Selection Guide**

Part No.	Dice	luminous Intensity [2] lv(mcd)@ 350mA  Min. Typ.		Фv (lm) [2] @ 350mA	Viewing Angle [1]
				Тур.	2 θ 1/2
AT2520QW10ZS-350MA	WHITE (InGaAIN)	10000	14000	55	120°

## Absolute Maximum Ratings at TA=25°C

Parameter	Symbol	Value	Unit
Power dissipation	Pt	1.25	W
Junction temperature[1]	TJ	120	°C
Operating Temperature	Тор	-40 To +100	°C
Storage Temperature	Tstg	-40 To +120	°C
DC Forward Current [1]	lF	350	mA
Peak Forward Current [2]	Iғм	500	mA
Thermal resistance [1] (Junction/ambient)	Rth j-a	70	°C/W
Thermal resistance [1] (Junction/solder point)	Rth j-s	26	°C/W
Electrostatic Discharge Threshold (HBM)		8000	V

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<sup>1.</sup>  $\theta$  1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity / luminous flux: +/-15%.

<sup>1.</sup> Results from mounting on metal core PCB,mounted on pc board-metal core PCB is recommend.for lowest thermal resistance. 2. 1/10 Duty Cycle, 0.1ms Pulse Width.

## Electrical / Optical Characteristics at Ta=25°C

Parameter	Symbol	Value	Unit
Chromaticity coordinate x acc.to CIE1931 IF=350mA [Typ.]	X [1]	0.31	-
Chromaticity coordinate y acc.to CIE1931 IF=350mA [Typ.]	y [1]	0.31	-
Forward Voltage IF=350mA [Min.]		2.8	
Forward Voltage IF=350mA [Typ.]	VF [2]	3.2	V
Forward Voltage Ir=350mA [Max.]		3.6	
Temperature coefficient of x IF=350mA, -10 ° C≤ T≤100 ° C [Typ.]	TCx	-0.15	10 <sup>-3</sup> /° C
Temperature coefficient of y IF=350mA, -10 ° C≤ T≤100 ° C [Typ.]	ТСу	-0.13	10 <sup>-3</sup> /° C
Temperature coefficient of VF IF=350mA, -10 ° C≤ T≤100 ° C [Typ.]	TCv	-3.2	mV/° C

### Notes:

## **Summary of Practical Pulsing Configurations with Typical Thermal Management.**

	Flash Pulse Current				
Flash Pulse Duration	0.35A	0.6A	1A	2A	
50 ms	OK	OK	OK	OK	
100 ms	OK	ОК	OK	-	
200 ms	OK	OK	-	-	
300 ms	OK	-	-	-	

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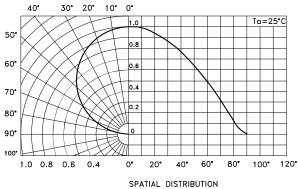
<sup>1.</sup> Measurement tolerance of the chromaticity coordinates is  $\pm 0.01$ .

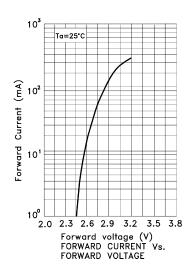
<sup>2.</sup>Forward Voltage: +/-0.1V.

OK Signifies a transient temperature change of less than 40°C.

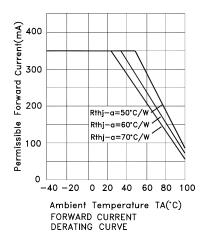
<sup>-</sup> Temperature change > 40°C, may require additional thermal management.

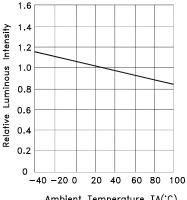
## AT2520QW10ZS-350MA





Luminous Intensity relative Value at IF=350mA 10 10³ 100 10 10<sup>2</sup> Forward current (mA) LUMINOUS INTENSITY Vs. FORWARD CURRENT





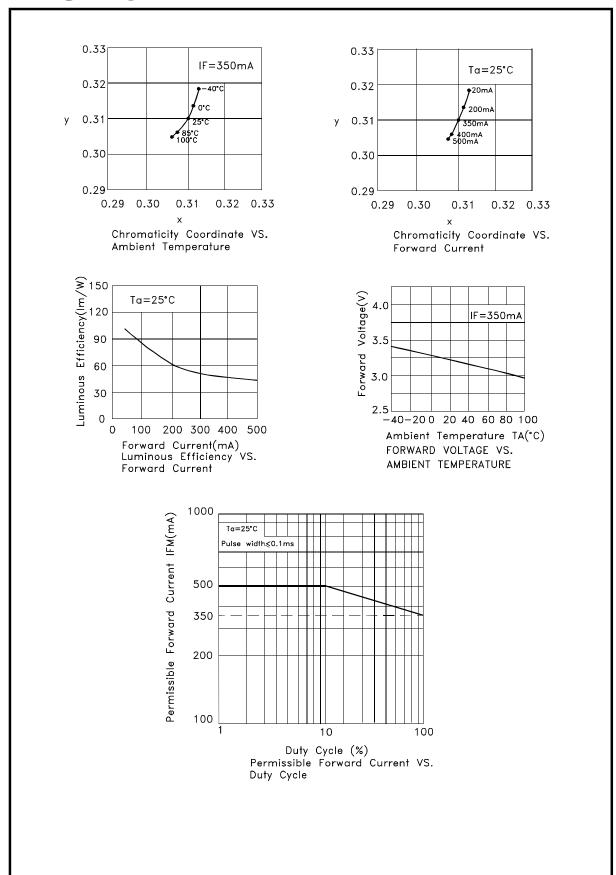
Ambient Temperature TA(°C) LUMINOUS INTENSITY VS. AMBIENT TEMPERATURE

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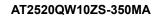
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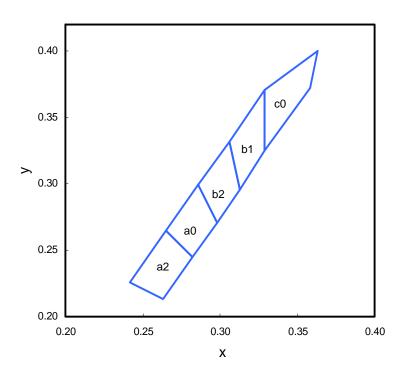


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Rank a2				
х	0.263	0.282	0.265	0.242
у	0.213	0.245	0.265	0.226

Rank b2					
х	0.298	0.313	0.306	0.286	
У	0.271	0.296	0.332	0.299	

Rank c0					
х	0.329	0.358	0.363	0.329	
у	0.325	0.372	0.400	0.371	

Rank a0					
x 0.282 0.298 0.286 0.265					
у	0.245	0.271	0.299	0.265	

Rank b1				
х	0.313	0.329	0.329	0.306
у	0.296	0.325	0.371	0.332

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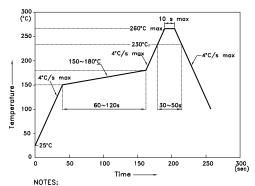
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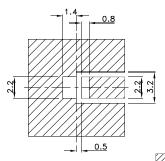
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



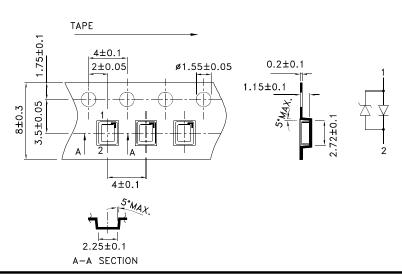
1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



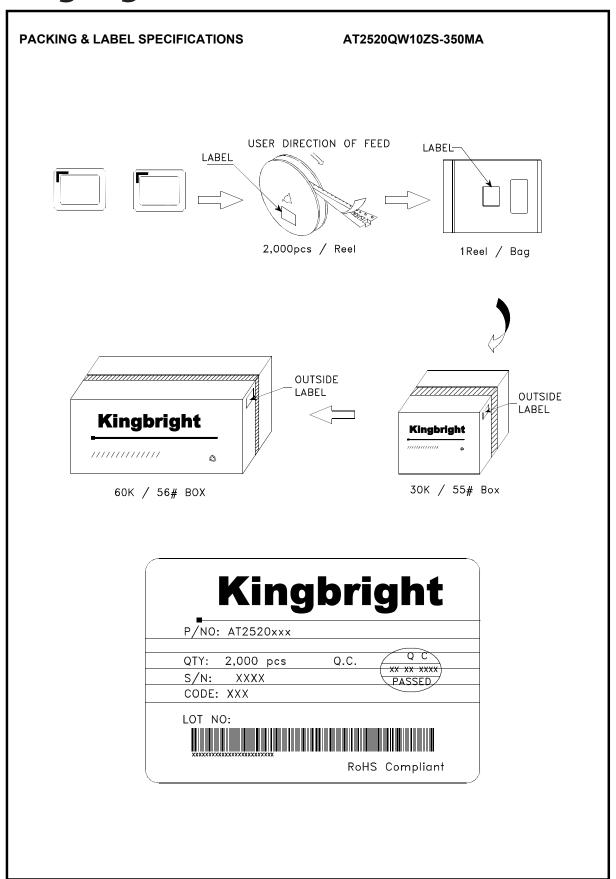
Solder resist

Tape Specifications (Units: mm)



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